

PCN Number: HC151401

Notification Date*: April 14, 2015

| Title: Change of Assembly Location ATA664251 | | | | | | | | | |
|---|--|--|---|----------------------------|-------------------|----------------|--|---|---|
| Product Identification: ATA664251-WGQW | | | | | | | | | |
| Reason for Change: | <input checked="" type="checkbox"/> Material / Composition | <input checked="" type="checkbox"/> Manufacturing Location | | | | | | | |
| | <input checked="" type="checkbox"/> Processing / Manufacturing | <input type="checkbox"/> Quality / Reliability | | | | | | | |
| | <input type="checkbox"/> Design / Firmware | <input type="checkbox"/> Logistics | | | | | | | |
| | <input checked="" type="checkbox"/> Datasheet | <input type="checkbox"/> Other: | | | | | | | |
| Change Description: | | | | | | | | | |
| <p>(1) In order to align its overall backend production strategy, ATMEL will introduce ASE Chung Li Taiwan as IC assembly subcontractors for automotive products. ASE Chungli Taiwan, has a long term experience as automotive assemblers, and is TS16949 certified and ATMEL qualified suppliers with existing business.</p> <p>The assembly of affected IC will be moved to ASE Chung Li Taiwan.</p> <p>Package comparison is available in the appendix.</p> <p>Marking will be changed from old ATMEL Logo to new ATMEL Logo</p> | | | | | | | | | |
| <p>(2) Change of Design Revision to improve System Level ESD Robustness</p> | | | | | | | | | |
| <p>(3) Datasheet change:</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 33%;">Test / Parameter / Feature</th> <th style="width: 33%;">Original value</th> <th style="width: 34%;">New value</th> </tr> </thead> <tbody> <tr> <td>VCC regulator under-voltage detection hysteresis, P. 17.11</td> <td>Parameter 17.11 LL=190 / T=300 / UL=400mV</td> <td>Parameter 17.11 LL=120 / T=160 / UL=300mV</td> </tr> </tbody> </table> | | | | Test / Parameter / Feature | Original value | New value | VCC regulator under-voltage detection hysteresis, P. 17.11 | Parameter 17.11 LL=190 / T=300 / UL=400mV | Parameter 17.11 LL=120 / T=160 / UL=300mV |
| Test / Parameter / Feature | Original value | New value | | | | | | | |
| VCC regulator under-voltage detection hysteresis, P. 17.11 | Parameter 17.11 LL=190 / T=300 / UL=400mV | Parameter 17.11 LL=120 / T=160 / UL=300mV | | | | | | | |
| Identification Method to Distinguish Change: | | | | | | | | | |
| <p>Devices can be tracked by lot number and date code which is part of the package marking. New ordering code has been created by adding a suffix or by changing to the new package code to manage backlog conversion.</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 50%;">Ordering code old</td> <td style="width: 50%;">Ordering code new</td> </tr> <tr> <td>ATA664251-WGQW</td> <td>ATA664251-WGQW-1</td> </tr> </table> | | | | Ordering code old | Ordering code new | ATA664251-WGQW | ATA664251-WGQW-1 | | |
| Ordering code old | Ordering code new | | | | | | | | |
| ATA664251-WGQW | ATA664251-WGQW-1 | | | | | | | | |
| Qualification Data: | <input type="checkbox"/> Available | <input checked="" type="checkbox"/> Will be available (mm/dd/yr): 04/24/2015 | <input type="checkbox"/> Not Applicable | | | | | | |

| | | | |
|---|---|--|---|
| Samples: | <input checked="" type="checkbox"/> Available | <input type="checkbox"/> Will be available (mm/dd/yr): | <input type="checkbox"/> Not Applicable |
| <p>Quantifiable Impact on Quality & Reliability: System level ESD Robustness will be improved.</p> | | | |
| <p>Forecasted Availability Date: 30 days after PPAP availability Target Backlog Conversion Date: 90 days after PPAP availability</p> <p><i>*All orders placed after the notification date are non-cancellable and non-returnable (NCNR).</i></p> | | | |
| <p>Atmel Contact: Please contact your Atmel Sales Representative or Distributor for additional information (when replying via e-mail please include the PCN number in subject line).</p> | | | |
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Appendix

ATA664251 package comparison

| Bill of material | | | |
|--|----------------------|----------------------|--|
| Item | UTAC | ASECL | Risk assessment |
| Mold compound | G770 | G700 | No risk, same family |
| Die attach | 8600 | EN4900 | No risk, both are silver filled epoxies |
| Die thickness die 1 Die thickness die 2 | 0,250 mm 0,250 mm | 0,178 mm 0,178 mm | No Risk, standard die thickness at ASECL |
| Lead frame material | EFTEC64T | C7025 | No risk, both are copper based alloys |
| Lead frame treatment | None | Rough copper | Improvement of robustnes (no Delamination) |
| Lead frame plating | Ag | Ag (photo resist) | Improvement of robustnes (no Delamination) |
| Bond wire material | Au | AuPd1% | No Risk, |
| Bond wire diameter | 20 microns | 20 microns | No Risk, same diameter |
| Plating | Matte Sn | Matte Sn | Matte Sn |

| Main Outline dimensions | | |
|-------------------------|-----------------|-----------------|
| Item | UTAC | ASECL |
| Package option | Wettable flanks | Wettable flanks |
| Package Thickness | 0,8mm – 0,9mm | 0,8mm - 0.9mm |
| Lead geometrie | | identical |
| Lead frame thickness | | identical |
| Exposed die pad | | identical |
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